

MOSFET – Power, Single N-Channel

60 V, 1.49 mΩ, 198 A

NTMJST1D4N06CL

Features

- Optimized Top Cool Package to Dissipate Heat from Top
- Small Footprint (5x7 mm) for Compact Designs
- Ultra Low $R_{DS(on)}$ to Improve System Efficiency
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage	V_{DSS}	60	V	
Gate-to-Source Voltage	V_{GS}	± 20	V	
Continuous Drain Current $R_{\theta JC}$ (Notes 1, 3)	Steady State	$T_C = 25^\circ\text{C}$	I_D 198	A
		$T_C = 100^\circ\text{C}$	140	
Power Dissipation $R_{\theta JC}$ (Note 1)	Steady State	$T_C = 25^\circ\text{C}$	P_D 116	W
		$T_C = 100^\circ\text{C}$	58	
Continuous Drain Current $R_{\theta JA}$ (Notes 1, 2, 3)	Steady State	$T_A = 25^\circ\text{C}$	I_D 42	A
		$T_A = 100^\circ\text{C}$	30	
Power Dissipation $R_{\theta JA}$ (Notes 1, 2)	Steady State	$T_A = 25^\circ\text{C}$	P_D 5.3	W
		$T_A = 100^\circ\text{C}$	2.6	
Pulsed Drain Current	$T_A = 25^\circ\text{C}, t_p = 10 \mu\text{s}$	I_{DM} 900	A	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55 to +175	$^\circ\text{C}$	
Source Current (Body Diode)	I_S	96	A	
Single Pulse Drain-to-Source Avalanche Energy ($I_{L(pk)} = 16.7 \text{ A}$)	E_{AS}	596	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T_L	260	$^\circ\text{C}$	

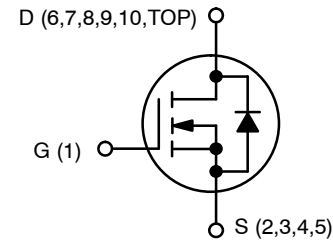
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

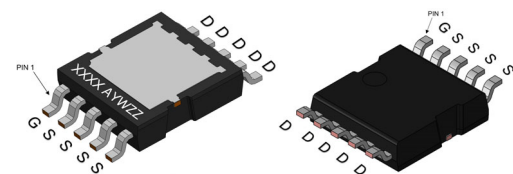
Parameter	Symbol	Value	Unit
Junction-to-Case – Steady State	$R_{\theta JC}$	0.3	$^\circ\text{C}/\text{W}$
Junction-to-Ambient – Steady State (Note 2)	$R_{\theta JA}$	28.5	
Junction-to-Heatsink Top – Steady State (Note 2)	$R_{\psi JH}$	1.3	
Junction-to-Drain Lead	$R_{\psi JL}$	4.7	
Junction-to-Source Lead	$R_{\psi JL}$	5.1	

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
2. 2s2p JEDEC51-7 standard PCB mounted to a 25x25x3 (mm) aluminum heatsink with a 12 w/mK TIM interface.
3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

$V_{(BR)DSS}$	$R_{DS(ON) MAX}$	$I_D MAX$
60 V	1.49 mΩ @ 10 V	198 A

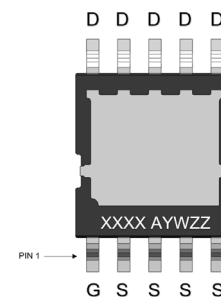


N-CHANNEL MOSFET



TPAK57
CASE 760AG

MARKING DIAGRAM



XXXX = Specific Device Code
 A = Assembly Location
 Y = Year
 W = Work Week
 ZZ = Assembly Lot Code

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J			27.9		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 60 V	T _J = 25 °C		10	μA
			T _J = 125°C		250	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±16 V			±100	nA

ON CHARACTERISTICS (Note 4)

Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250 μA	1.2		2	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J			-6.11		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 50 A		1.27	1.49	mΩ
Forward Transconductance	g _{FS}	V _{DS} = 5 V, I _D = 50 A		217		S

CHARGES, CAPACITANCES & GATE RESISTANCE

Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 25 V		6555		pF
Output Capacitance	C _{OSS}			3695		
Reverse Transfer Capacitance	C _{RSS}			37.5		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 50 A		92.2		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 48 V; I _D = 50 A		9.5		
Gate-to-Source Charge	Q _{GS}			16.2		
Gate-to-Drain Charge	Q _{GD}			10.5		
Plateau Voltage	V _{GP}			2.8		V

SWITCHING CHARACTERISTICS (Note 5)

Turn-On Delay Time	t _{d(ON)}	V _{GS} = 10 V, V _{DS} = 48 V, I _D = 50 A, R _G = 1.0 Ω		16		ns
Rise Time	t _r			25		
Turn-Off Delay Time	t _{d(OFF)}			60		
Fall Time	t _f			11		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 50 A	T _J = 25°C		0.8	1.2	V
			T _J = 125°C		0.66		
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _S /dt = 100 A/μs, I _S = 50 A		82.1		ns	
Charge Time	t _a			42.4			
Discharge Time	t _b			40			
Reverse Recovery Charge	Q _{RR}			119			nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.

5. Switching characteristics are independent of operating junction temperatures.

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TYPICAL CHARACTERISTICS

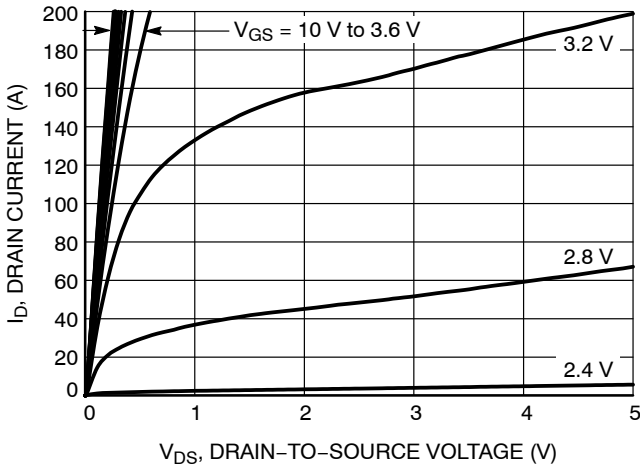


Figure 1. On-Region Characteristics

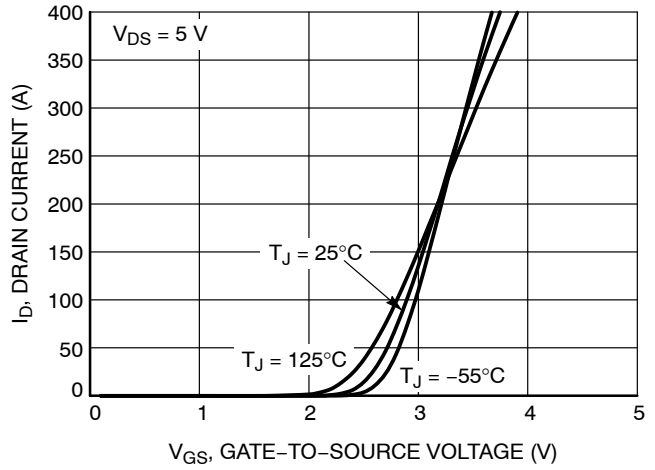


Figure 2. Transfer Characteristics

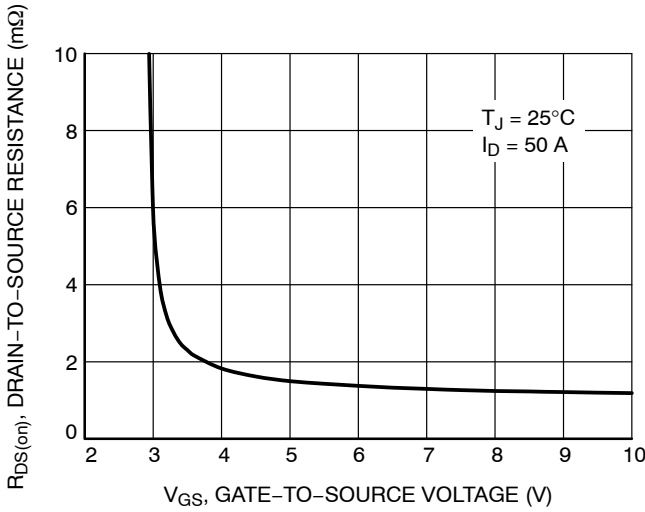


Figure 3. On-Resistance vs. Gate-to-Source Voltage

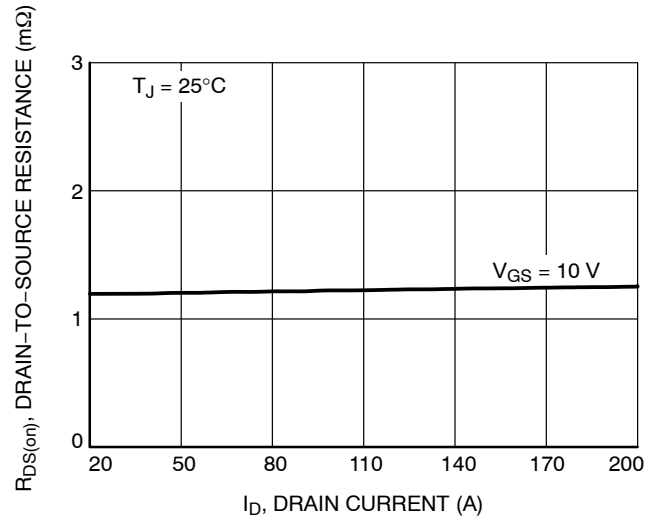


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

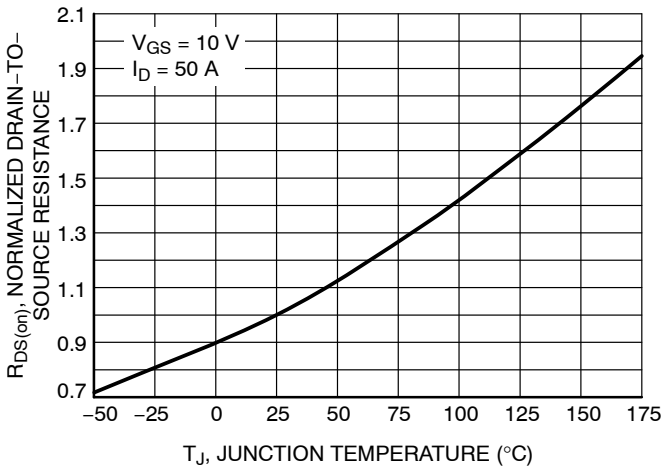


Figure 5. On-Resistance Variation with Temperature

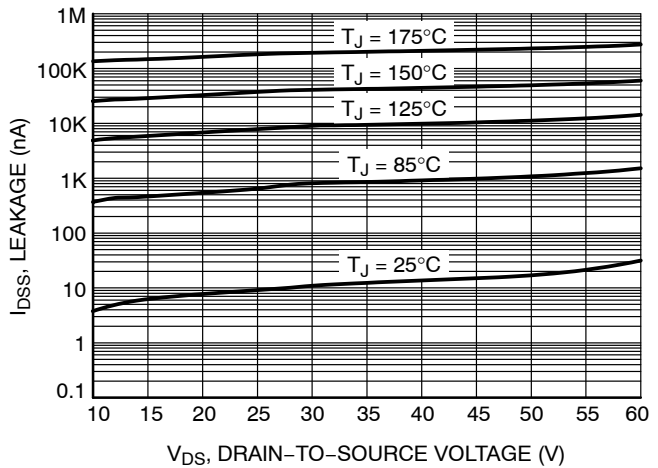


Figure 6. Drain-to-Source Leakage Current vs. Voltage

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TYPICAL CHARACTERISTICS

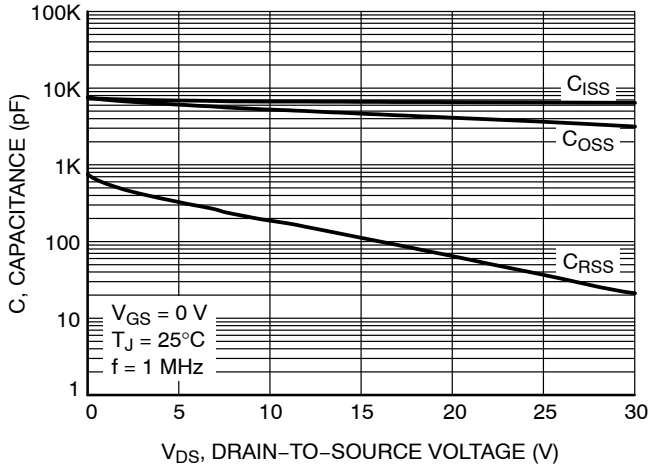


Figure 7. Capacitance Variation

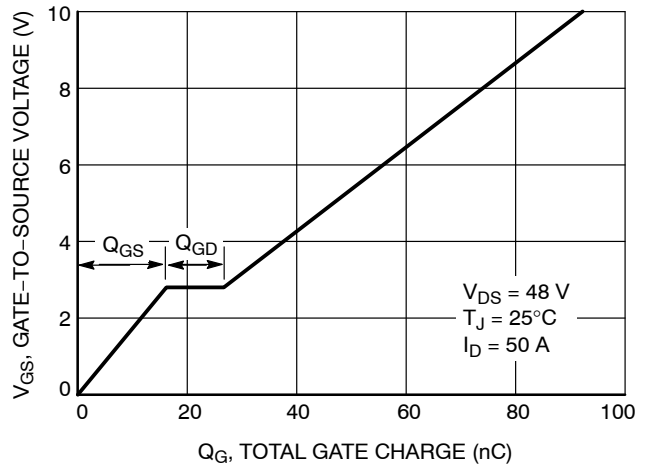


Figure 8. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

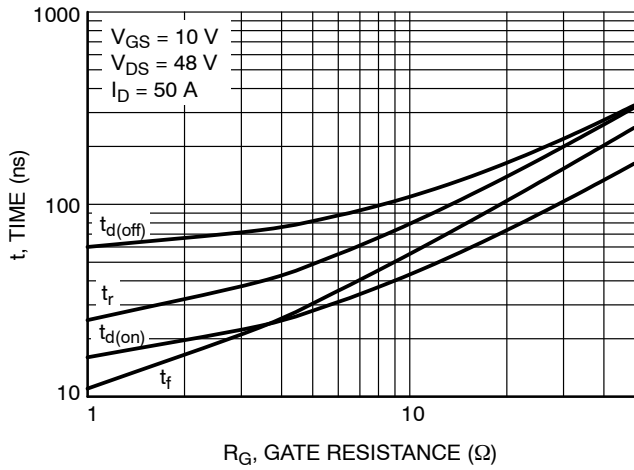


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

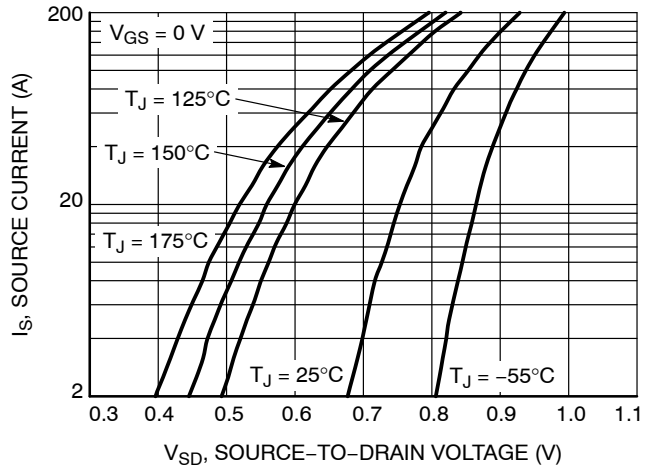


Figure 10. Diode Forward Voltage vs. Current

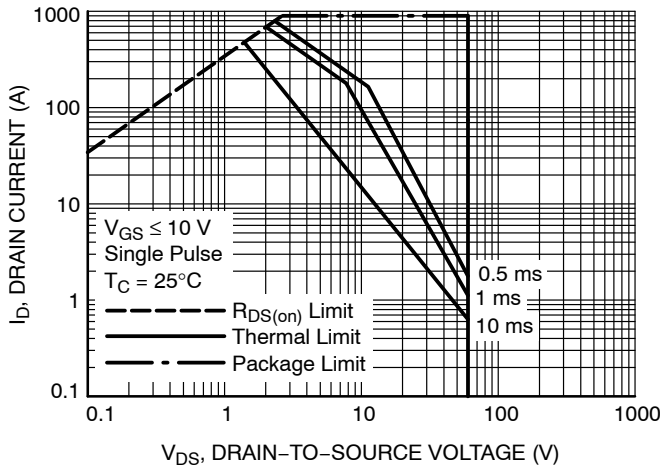


Figure 11. Safe Operating Area

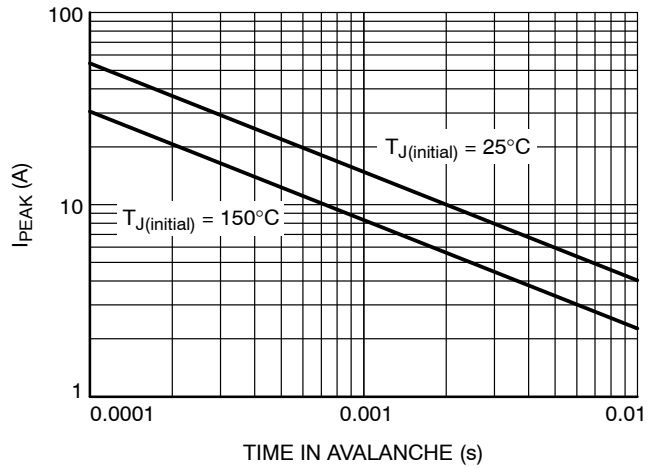


Figure 12. I_{PEAK} vs. Time in Avalanche

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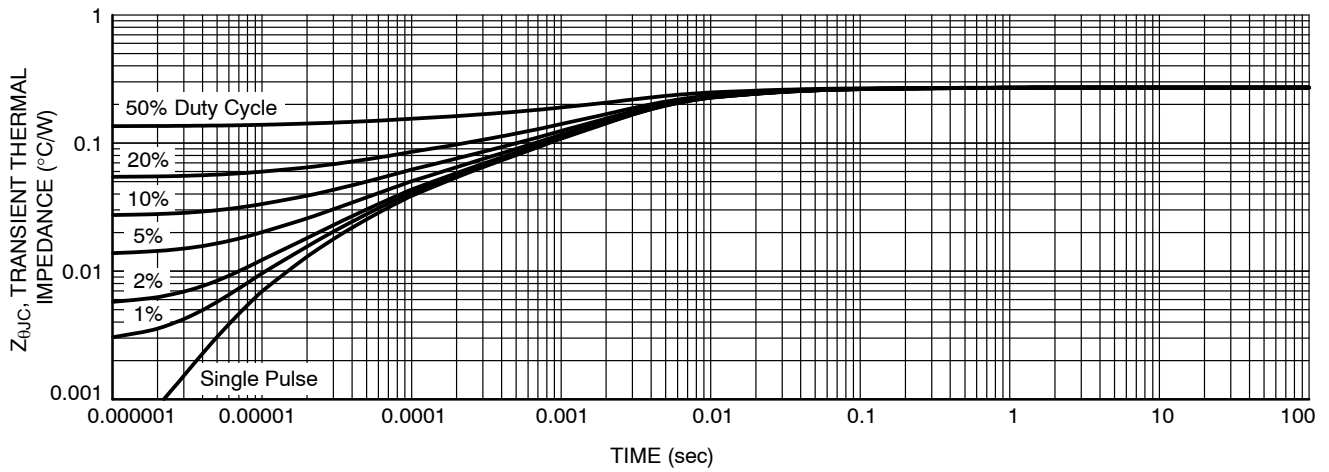


Figure 13. Thermal Characteristics

DEVICE ORDERING INFORMATION

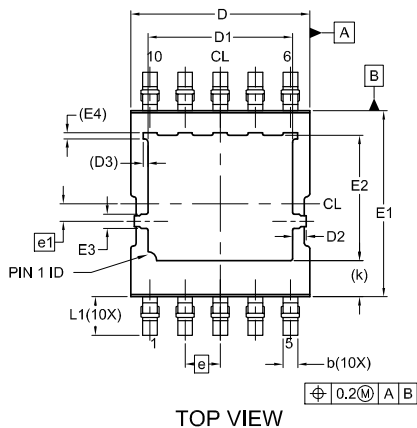
Device	Marking	Package	Shipping [†]
NTMJST1D4N06CLTXG	1D46L	TCPAK57 (Pb-Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

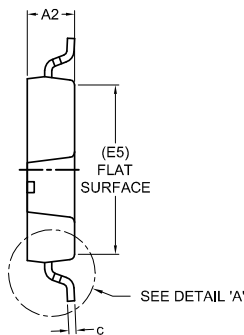
NTMJST1D4N06CL

PACKAGE DIMENSIONS

TCPAK10 5.1x7.5, 1.0P
CASE 760AG
ISSUE D



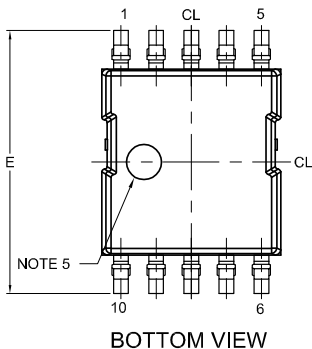
TOP VIEW



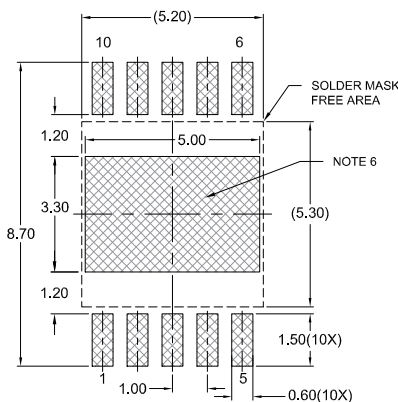
SIDE VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. UNIT DIMENSION: MILLIMETERS
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.150mm PER SIDE.
4. DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
5. OPTIONAL MOLD FEATURE.
6. LAND PAD UNDER THE PACKAGE BODY IS FOR MECHANICAL SUPPORT ONLY. SOLDER CONNECTION IS NOT REQUIRED.
7. DIMENSION A1 IS THE LEAD STAND-OFF FROM THE BOTTOM SURFACE OF THE PACKAGE BODY.



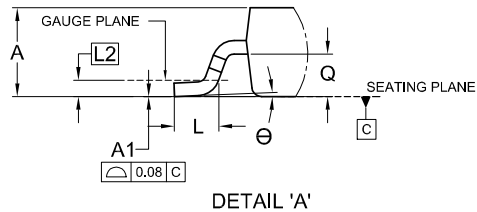
BOTTOM VIEW



LAND PAD RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.30	1.35	1.45
A1	-0.05	0.00	0.05
A2	1.30	1.35	1.40
b	0.36	0.41	0.46
c	0.16	0.21	0.26
D	5.00	5.10	5.20
D1	4.02	4.12	4.22
D2	0.30	0.40	0.50
D3	0.14 REF		
E	7.40	7.50	7.60
E1	5.20	5.30	5.40
E2	3.47	3.57	3.67
E3	0.30	0.40	0.50
E4	0.17 REF		
E5	4.82 REF		
e	1.00 BSC		
e1	0.50 BSC		
k	1.03 REF		
L	0.49	0.69	0.89
L1	0.90	1.10	1.30
L2	0.25 BSC		
Q	0.60	0.65	0.70
Θ	0°	2.5°	5°



DETAIL 'A'

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